



# Chip-Capacitor Manufacturing Location Change for Defense-Grade XQ Product

XCN18019 (v1.0) July 16, 2018

Product Change Notice – FYI

## Overview

The purpose of this notification is to communicate that Xilinx® defense-grade product chip-capacitor manufacturer will change the manufacturing location for chip-capacitors used in Xilinx defense-grade “XQ” products.

## Description

Xilinx defense-grade product chip-capacitor manufacturer will change its chip-capacitor manufacturing location for various capacitors. Xilinx has worked with the supplier to qualify this capacitor manufacturing location. This change enables Xilinx to better support long-term customer demand. There is no change in the fit, form, function or reliability of the capacitor with this change.

## Products Affected

This change affects all speeds, temperature variations of defense-grade “XQ” product grades of Virtex®-4, Virtex®-5, Virtex®-6, Virtex®-7, Kintex®-7 and Zynq®-7000 as defined in the tables below. Any associated specification control document (SCD) versions of the standard part numbers are also affected.

Table 1: Virtex-4Q Device-Packages

Device	Package-Pin
XQ4VLX60	FF1148
XQ4VLX100	
XQ4VLX160	
XQ4VLX80	
XQ4VSX55	

Device	Package-Pin
XQ4VFX60	FF1152
XQ4VFX100	
XQ4VFX60	EF672

Table 2: Virtex-5Q Device-Packages

Device	Package-Pin
XQ5VFX70T	EF665
XQ5VSX50T	
XQ5VLX85	EF676
XQ5VLX110	
XQ5VLX110T	EF1136
XQ5VLX155T	
XQ5VFX70T	
XQ5VFX100T	
XQ5VSX95T	

Device	Package-Pin
XQ5VLX110	EF1153
XQ5VLX220T	EF1738
XQ5VLX330T	
XQ5VFX100T	
XQ5VFX130T	FF1738
XQ5VFX200T	
XQ5VSX240T	

Table 3: Virtex-6Q Device-Packages

Device	Package-Pin
XQ6VLX130T	RF1156
XQ6VLX240T	
XQ6VSX315T	
XQ6VSX475T	
XQ6VLX130T	RF784
XQ6VLX240T	

Device	Package-Pin
XQ6VLX240T	RF1759
XQ6VLX550T	
XQ6VSX315T	
XQ6VSX475T	

Table 4: Virtex-7Q Devices-Packages

Device	Package-Pin
XQ7V585T	RF1157
XQ7VX330T	
XQ7VX690T	
XQ7VX690T	RF1158
XQ7V585T	RF1761
XQ7VX330T	
XQ7VX485T	
XQ7VX690T	
XQ7VX485T	RF1930
XQ7VX690T	
XQ7VX980T	

Table 5: Kintex-7Q and Zynq-7000 Devices-Packages

Device	Package-Pin
XQ7Z030	RB484
XQ7Z100	RF1156
XQ7K325T	RF676
XQ7K410T	
XQ7Z030	
XQ7Z045	
XQ7K325T	RF900
XQ7K410T	
XQ7Z045	
XQ7Z100	

## Key Dates and Ordering Information

Xilinx will start manufacturing devices with capacitors from the new capacitor manufacturing location after the PCN-FYI release date.

## Qualification Data

Xilinx has worked with the chip-capacitor supplier to perform chip-capacitor level qualification testing. All the necessary qualification data will be available upon request.

## Response

No response is required.

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## Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
07/16/2018	1.0	Initial release

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